Top Port Digital Silicon Microphone

DESCRIPTION

The WM7211 is a low-profile silicon digital microphone. It offers high Signal-to-Noise Ratio (SNR) and low power consumption and is suited to a wide variety of consumer applications.

The WM7211 incorporates Cirrus's proprietary CMOS/MEMS membrane technology, offering high reliability and high performance in a miniature, low-profile package. The WM7211 is designed to withstand the high temperatures associated with automated flow solder assembly processes. (Note that conventional microphones can be damaged by this process.)

The WM7211 incorporates a high performance ADC, which outputs a single-bit data stream using Pulse Density Modulation (PDM) encoding. The WM7211 supports selectable left/right channel assignment for a two-channel digital microphone interface, enabling efficient connection of multiple microphones in stereo/array configurations.

The WM7211 offers tight tolerance on the microphone sensitivity, giving reduced variation between parts. This removes the need for in-line production calibration of part-to-part microphone variations.
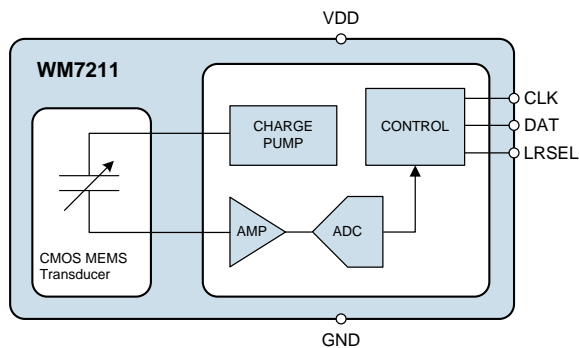
FEATURES

- High SNR (61dB)
- Low variation in sensitivity (±1dB tolerance)
- Low current consumption
    - 2µA (Sleep)
    - 735µA (Normal operation)
- PDM digital audio output
- Stereo/array operation
- Proprietary ADC technology
    - Reduced clock jitter sensitivity
    - Low noise floor
    - Stable in overload condition
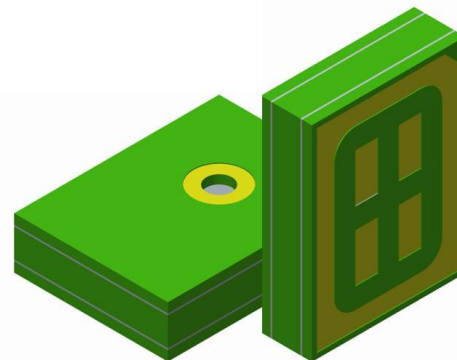- Top Port LGA Package
- 1.64V to 3.7V supply

APPLICATIONS

- Mobile telephone handsets
- Portable computers
- Portable media players
- Digital still cameras
- Digital video cameras
- Bluetooth headsets
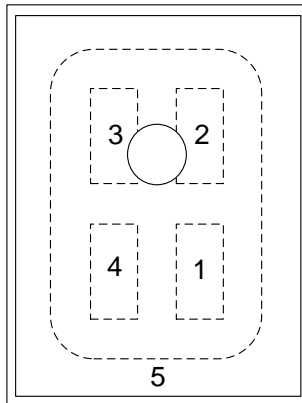- Portable navigation devices

BLOCK DIAGRAM

3D VIEW

4.00mm x 3.00mm x 1.00mm LGA package

Rev 4.0
MAR '16

TABLE OF CONTENTS

WM7211E

PIN CONFIGURATION

Top View

PIN DESCRIPTION

PIN	NAME	TYPE	DESCRIPTION
1	VDD	Supply	Power Supply
2	LRSEL	Digital Input	Channel Select 0 = Data output following falling CLK edge 1 = Data output following rising CLK edge Internal pull-down holds this pin at logic 0 when not connected
3	CLK	Digital Input	Clock input
4	DAT	Digital Output	PDM Data Output
5	GND	Supply	Ground

ORDERING INFORMATION

ORDER CODE	TEMPERATURE RANGE	PACKAGE	MOISTURE SENSITIVITY LEVEL	PEAK SOLDERING TEMPERATURE
WM7211IMSE/RV	-40 to +100°C	LGA (tape and reel)	MSL2A	+260°C

Note:

Reel Quantity = 4800

All devices are Pb-free and Halogen free.

ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings are stress ratings only. Permanent damage to the device may be caused by continuously operating at or beyond these limits. Device functional operating limits and guaranteed performance specifications are given under Electrical Characteristics at the test conditions specified.

ESD Sensitive Device. This device is manufactured on a CMOS process. It is therefore generically susceptible to damage from excessive static voltages. Proper ESD precautions must be taken during handling and storage of this device.

Cirrus tests its package types according to IPC/JEDEC J-STD-020 for Moisture Sensitivity to determine acceptable storage conditions prior to surface mount assembly. These levels are:

MSL1 = unlimited floor life at <30°C / 85% Relative Humidity. Not normally stored in moisture barrier bag.
MSL2 = out of bag storage for 1 year at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.
MSL2A = out of bag storage for 4 weeks at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.
MSL3 = out of bag storage for 168 hours at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.

The Moisture Sensitivity Level for each package type is specified in Ordering Information.

CONDITION	MIN	MAX
Supply Voltage (VDD)	-0.3V	+4.2V
Voltage range digital inputs (LRSEL, CLK)	GND - 0.3V	VDD + 0.3V
Operating temperature range, T_A	-40°C	+100°C
Storage temperature prior to soldering	30°C max / 60% RH max	
Storage temperature after soldering	-40°C	+100°C

IMPORTANT ASSEMBLY GUIDELINES

Do not put a vacuum over the port hole of the microphone. Placing a vacuum over the port hole can damage the device.

Do not board wash the microphone after a re-flow process. Board washing and the associated cleaning agents can damage the device. Do not expose to ultrasonic cleaning methods.

Do not use vapour phase re-flow process. The vapour can damage the device.

Please refer to application note WAN0273 (MEMS MIC Assembly and Handling Guidelines) for further assembly and handling guidelines.

RECOMMENDED OPERATING CONDITIONS

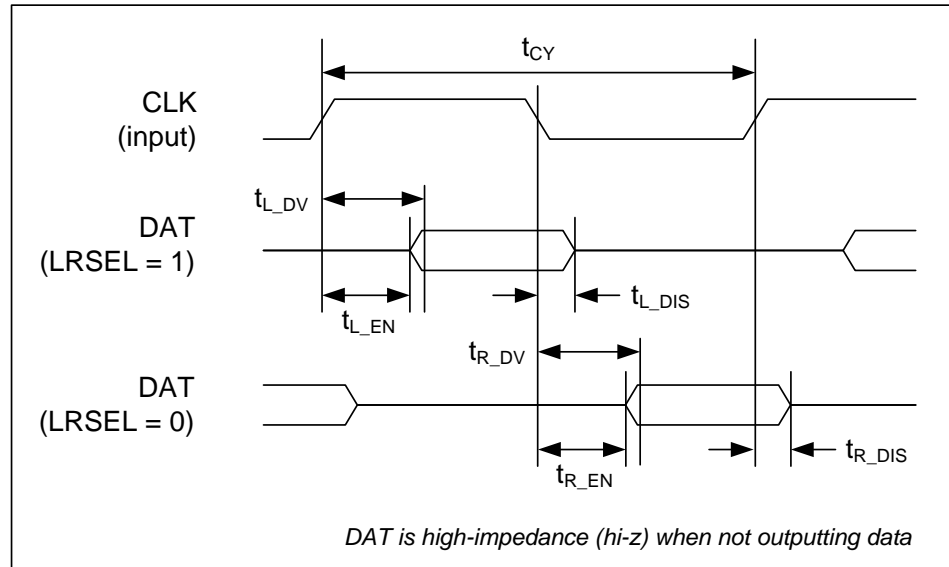| PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT
VDD Supply Range	VDD	1.64		3.7	V
Ground	GND		0		V
Clock Frequency	F_{CLK}	1		3.25	MHz

ACOUSTIC AND ELECTRICAL CHARACTERISTICS

Test Conditions: VDD=1.8V, 1kHz test signal, CLK=2.4MHz, T_A = 25°C, unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Directivity			Omni-directional			
Polarity (see note)		Positive sound pressure	Decreasing density of 1s			
Sensitivity	S	94dB SPL	-27	-26	-25	dBFS
Acoustic Overload		No load, THD < 10%		120		dB SPL
Total Harmonic Distortion	THD	94dB SPL		0.1		%
		114dB SPL		0.5		
		117.5dB SPL		1		
Signal to Noise Ratio	SNR	A-weighted		61		dB
Dynamic Range	DR	A-weighted		84.5		dB
Acoustic Noise Floor		A-weighted		33		dB SPL
Electrical Noise Floor		A-weighted		-87		dBFS
Frequency Response		+3dB high frequency		17000		Hz
Frequency Response Flatness		200Hz to 8kHz	-1		+1	dB
Power Supply Rejection	PSR	217Hz Square Wave 100mV (peak-peak)		-75		dBFS
Digital Input / Output						
CLK Input HIGH Level	V_{IH}		0.65 x VDD			V
CLK Input LOW Level	V_{IL}				0.35 x VDD	V
DAT Output HIGH Level	V_{OH}	I_{OH} = +1mA	0.9 x VDD			V
DAT Output LOW Level	V_{OL}	I_{OL} = -1mA			0.1 x VDD	V
Input capacitance (CLK)	C_{IN}			0.5		pF
Input Leakage					1	µA
Maximum load capacitance (DAT)	C_{LOAD}				100	pF
Short Circuit Output Current	I_{SC}	DAT connected to GND			10	mA
Miscellaneous						
Current Consumption	I_{VDD}	Active Mode		735		µA
		SLEEP Mode		2	10	
Start-up Time		From OFF		10		ms
		From SLEEP		10		
CLK Sleep Frequency					1.0	kHz

Note: The WM7211 generates a single-bit digital (PDM) output in response to the acoustic input. A positive sound pressure on the diaphragm generates a decreasing density of 1's in the PDM stream (i.e. there is a phase inversion between the acoustic input and the digital output.)

TERMINOLOGY

1. Sensitivity (dBFS) – Sensitivity is a measure of the microphone output response to the acoustic pressure of a 1kHz 94dB SPL (1Pa RMS) sine wave. This is referenced to the output Full Scale Range (FSR) of the microphone.

2. Full Scale Range (FSR) - Sensitivity, Electrical Noise Floor and Power Supply Rejection are measured with reference to the output Full Scale Range (FSR) of the microphone. FSR is defined as the amplitude of a 1kHz sine wave output whose positive peak value reaches 100% density of logic 1s and whose negative peak value reaches 0% density of logic 1s. This is the largest 1kHz sine wave that will fit in the digital output range without clipping. Note that, because the definition of FSR is based on a sine wave, it is possible to support a square wave test signal output whose level is +3dBFS.

3. Total Harmonic Distortion (%) – THD is the ratio of the RMS sum of the harmonic distortion products in the specified bandwidth (see note below) relative to the RMS amplitude of the fundamental (ie. test frequency) output.

4. Signal-to-Noise Ratio (dB) – SNR is a measure of the difference in level between the output response of a 1kHz 94dB SPL sine wave and the idle noise output.

5. Dynamic Range (dB) – DR is the ratio of the 1% THD microphone output level (in response to a sine wave input) and the idle noise output level.

6. All performance measurements are carried out within a 20Hz to 20kHz bandwidth and, where noted, an A-weighted filter. Failure to use these filters will result in higher THD and lower SNR values than are found in the Acoustic and Electrical Characteristics. The brick wall filter removes out of band noise.

7. Sleep Mode is enabled when the CLK input is below the CLK Sleep Frequency noted above. This is a power-saving mode. Normal operation resumes automatically when the CLK input is above the CLK Sleep Frequency. Note that the VDD supply is still required in Sleep mode.

AUDIO INTERFACE TIMING

DAT is high-impedance (hi-z) when not outputting data

Figure 1 Digital Microphone Interface Timing

Test Conditions

The following timing information is valid across the full range of recommended operating conditions.

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT
Digital Microphone Interface Timing					
CLK cycle time	t_{CY}	308		1000	ns
CLK duty cycle		60:40		40:60	
CLK rise/fall time				6	ns
DAT enable from rising CLK edge (LRSEL = 1)	t_{L_EN}	14			ns
DAT valid from rising CLK edge (LRSEL = 1)	t_{L_DV}	20		90	ns
DAT disable from falling CLK edge (LRSEL = 1)	t_{L_DIS}			16	ns
DAT enable from falling CLK edge (LRSEL = 0)	t_{R_EN}	14			ns
DAT valid from falling CLK edge (LRSEL = 0)	t_{R_DV}	20		90	ns
DAT disable from rising CLK edge (LRSEL = 0)	t_{R_DIS}			16	ns

Notes:

1. The DAT output is high-impedance when not outputting data; this enables the outputs of two microphones to be connected together, with the data from one microphone interleaved with the data from the other. (The microphones must be configured to transmit on opposite channels in this case.)

2. In a typical configuration, the Left channel is transmitted following the rising CLK edge (LRSEL = 1). In this case, the Left channel should be sampled by the receiving device on the falling CLK edge.

3. Similarly, the Right channel is typically transmitted following the falling CLK edge (LRSEL = 0). In this case, the Right channel should be sampled by the receiving device on the rising CLK edge.

4. The WM7211 operating mode is selected according to the CLK frequency; see "Acoustic and Electrical Characteristics" for further details.

TYPICAL PERFORMANCE
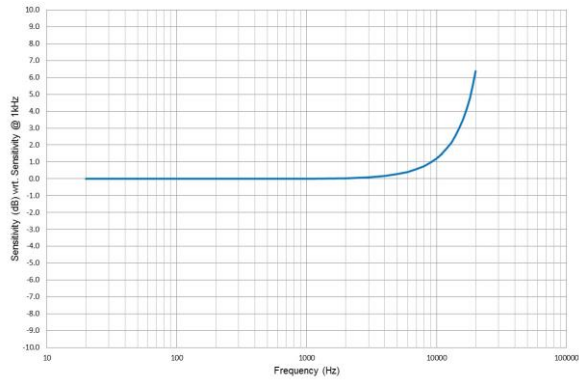
Sensitivity vs. Frequency
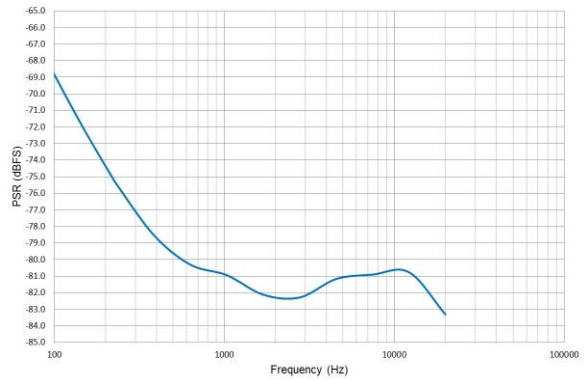
PSR vs. Frequency
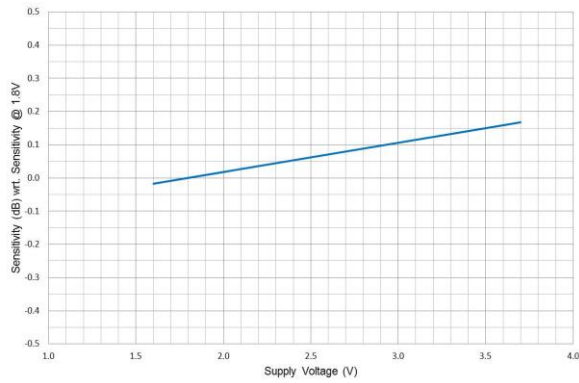
Sensitivity vs. Supply Voltage
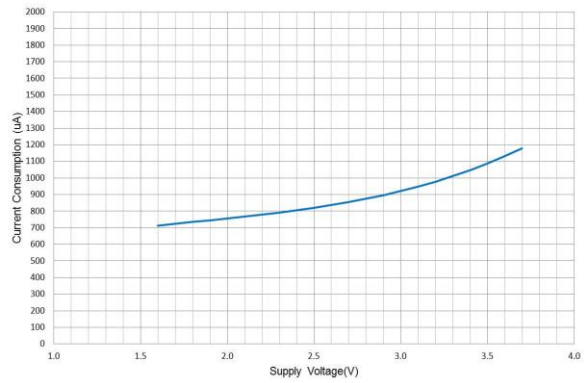
Current Consumption vs. Supply Voltage
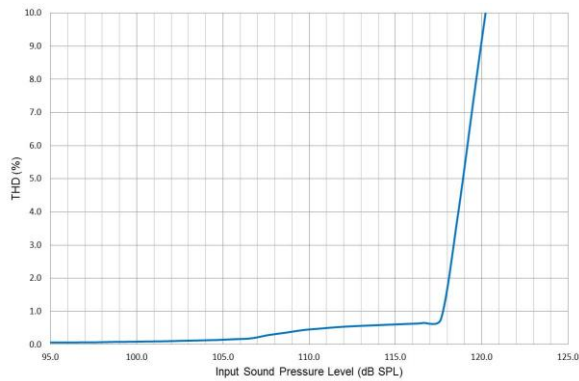
THD vs. Sound Pressure Level

APPLICATIONS INFORMATION

RECOMMENDED EXTERNAL COMPONENTS

It is recommended to connect a 0.1µF decoupling capacitor between the VDD and GND pins of the WM7211. A ceramic 0.1µF capacitor with X7R dielectric or better is suitable. The capacitor should be placed as close to the WM7211 as possible.

OPTIMISED SYSTEM RF DESIGN

For optimised RF design please refer to document WAN0278 (Recommended PCB Layout for Microphone RF Immunity in Mobile Cell Phone Applications) for further information.

CONNECTION TO A CIRRUS AUDIO CODEC

Cirrus provides a range of audio CODECs incorporating a digital microphone input interface; these support direct connection to digital microphones such as the WM7211.

Stereo connection of two WM7211 digital microphones is illustrated in Figure 2.

Further information on Cirrus audio CODECs is provided in the respective product datasheet, which is available from the Cirrus website.
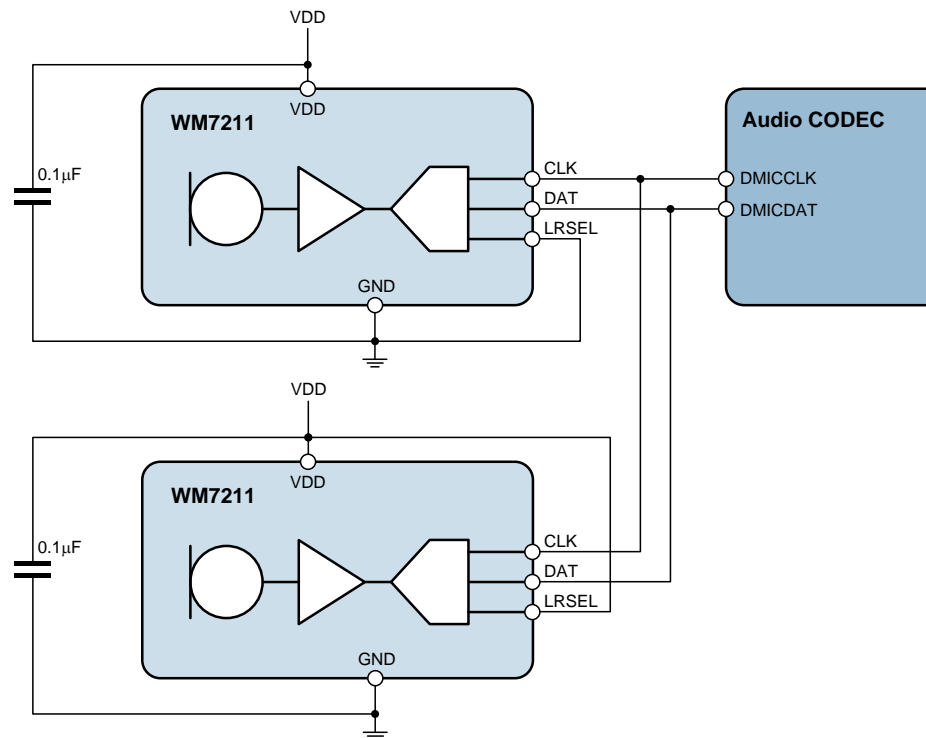
Figure 2 Stereo WM7211 Digital Microphone Connection

PCB LAND PATTERN AND PASTE STENCIL

The recommended PCB Land Pattern and Paste Stencil Pattern for the WM7211 microphone are shown in Figure 3 and Figure 4.

See also Application Note WAN0284 (General Design Considerations for MEMS Microphones) for further details of PCB footprint design.

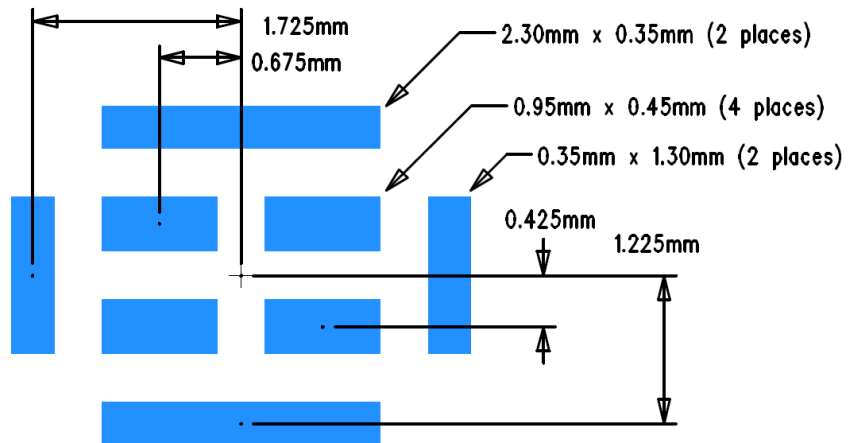Full definition of the package dimensions is provided in the "Package Dimensions" section.

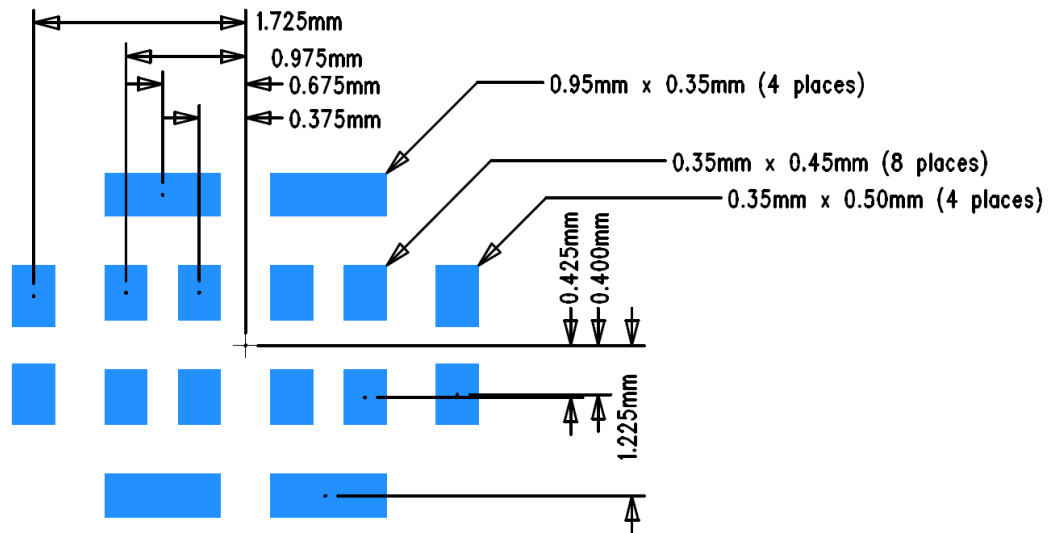**Figure 3 DM96 - PCB Land Pattern, Top View**

Figure 4 DM096 - Paste Stencil Pattern, Top View

PACKAGE DIMENSIONS

Rev	Revision History Description	Originator	Date
F	SRO tolerance, hidden lines in bottom view. Port hole tolerance	TS	02/04/14
G	Port Hole SRO diameter change	TS	11/04/14
H	Rebranded to Cirrus Logic.	MR	17/03/15

4x 0.95 x 0.45

⌀ 0.10 Ⓜ C A B
⌀ 0.05 Ⓜ C

0.40
0.10
0.35
0.35
0.10
1.35
0.40
5
2
3
1
4
1.33
0.85
1.08
4x R0.40

Bottom View

3.80 x 2.80

⌀ 0.10 Ⓜ C A B
⌀ 0.05 Ⓜ C

0.30 x 45 °

Cirrus Logic

Drawing Type		Package Style			
POD		CA MEMS			
Pitch	I/O Count	Body X	Body Y	Body Z	
0.85	5	4.00	3.00	1.00	
Size	Scale	Drawing Number			Rev
A4	20:1	DM096			H
Sheet					
1 of 1					

Unless otherwise specified
dimensions are in millimetres

Decimal
X.X ±0.1
X.XX ±0.05
X.XXX ±0.03

Angular
±1°

Interpret DIM and Tol per
ASME Y14.5M - 1994

3.00±0.10

B

1.10
PNP Vacuum
Hole

⌀ 0.50±0.05
Port Hole

⌀ 0.85
SRO of Port Hole
⌀ ⌀ 0.24 Ⓜ

Top View

// 0.10 C

1.00±0.10

C

Side View

4.00±0.10

⌀ 0.10 C

A

1.50

1.50

IMPORTANT NOTICE

Contacting Cirrus Logic Support
For all product questions and inquiries, contact a Cirrus Logic Sales Representative.
To find one nearest you, go to www.cirrus.com.

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REVISION HISTORY

DATE	REV	DESCRIPTION OF CHANGES	PAGE	CHANGED BY
31/01/11	2.0	First Release		PF
18/02/11	2.0	Confidential added to headers and footers		JMacD
26/04/11	2.1	Updated the PSRR, sleep mode, start up time from off Updated frequency response curve and the +3dB point to 17000hz Updated the THD % Updated all the LRSEL description , and figure 1 Added the notes on Updated reel quantity		KC
27/04/11	2.1	Current consumption / Active Mode changed to 650 µA		JMacD
02/05/11	2.2	Package Drawing updated.		JMacD
20/12/11	2.3	Introduced E variant with sensitivity +/-1dB Added E variant ordering info Added voltage range digital input Updated the CODEC to WM8994 Added Reference to WAN_0273		KC
19/01/12	2.3	Package Diagram updated to DM096C – formatting updates.		JMacD
23/08/12	2.4	Package Diagram updated to DM096D		JMacD
16/05/13	2.5	Package Diagram updated to DM096E		JMacD
08/11/13	3.1	Product Status updated to Pre Production Updated CODEC reference to WM8280.		JMacD
18/12/13	3.1	Acoustic and Electrical Characteristics updated: Polarity and Note added.		MR
03/10/14	3.2	Updates throughout the whole document		PH
16/03/15	3.3	Typical performance graphs updated PCB Stencil and Land Pattern drawings updated Package Outline Drawing updated	8 10 11	PH
21/04/15	3.4	Package Outline Diagram updated	11	PH
02/10/15	4.0	Updated to 'Production' status		PH